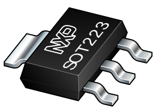


BUK7880-55

N-channel TrenchMOS standard level FET

16 March 2016 Product data sheet

1. General description

Standard level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

2. Features and benefits

- AEC Q101 compliant
- Electrostatically robust due to integrated protection diodes
- Low conduction losses due to low on-state resistance

3. Applications

- Automotive and general purpose power switching

4. Quick reference data

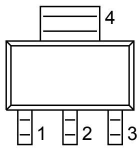
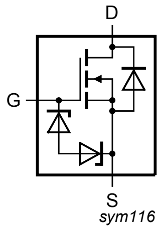
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 150$ °C		-	-	55	V
I_D	drain current	$T_{sp} = 25$ °C		-	-	7.5	A
P_{tot}	total power dissipation	$T_{sp} = 25$ °C; Fig. 4		-	-	8.3	W
Static characteristics							
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10$ V; $I_D = 5$ A; $T_j = 25$ °C		-	65	80	mΩ
Avalanche ruggedness							
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 2.5$ A; $V_{sup} \leq 25$ V; $R_{GS} = 50$ Ω; $V_{GS} = 10$ V; $T_{j(init)} = 25$ °C; unclamped		-	-	30	mJ

Scan or click this QR code to view the latest information for this product

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 SC-73 (SOT223)	
2	D	drain		
3	S	source		
4	D	mounting base; connected to drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK7880-55	SC-73	plastic surface-mounted package with increased heatsink; 4 leads	SOT223
BUK7880-55/CU	SC-73	plastic surface-mounted package with increased heatsink; 4 leads	SOT223

7. Marking

Table 4. Marking codes

Type number	Marking code
BUK7880-55	
BUK7880-55/CU	xxYWW 78055

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 150$ °C		-	55	V
V_{DGR}	drain-gate voltage	R_{GS} = 20 kΩ		-	55	V
V_{GS}	gate-source voltage			-16	16	V
P_{tot}	total power dissipation	T_{sp} = 25 °C; Fig. 4		-	8.3	W
I_D	drain current	T_{sp} = 25 °C		-	7.5	A
		T_{sp} = 100 °C		-	4.7	A

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Symbol	Parameter	Conditions		Min	Max	Unit
I_{DM}	peak drain current	T_{sp} = 25 °C; pulsed		-	40	A
T_{stg}	storage temperature			-55	150	°C
T_j	junction temperature			-55	150	°C
Source-drain diode						
I_S	source current	T_{sp} = 25 °C		-	7.5	A
I_{SM}	peak source current	pulsed; T_{sp} = 25 °C		-	40	A
Avalanche ruggedness						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	I_D = 2.5 A; V_{sup} ≤ 25 V; R_{GS} = 50 Ω; V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; unclamped		-	30	mJ
Electrostatic discharge						
V_{esd}	electrostatic discharge voltage	HBM; C = 100 pF; R = 1.5 kΩ		-	2	kV

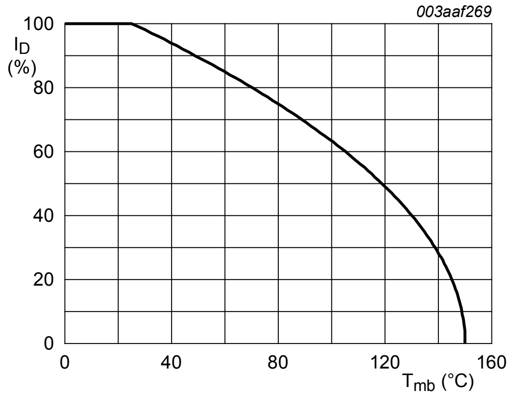
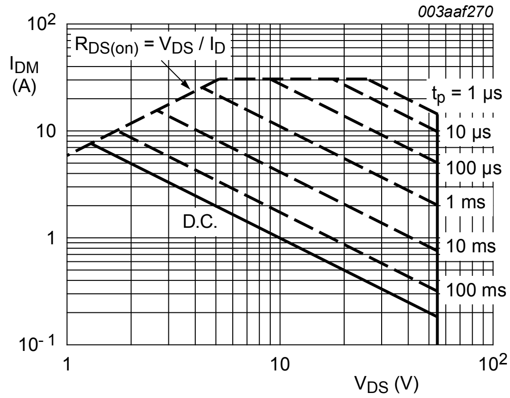


Fig. 1. Normalized continuous drain current as a function of solder point temperature

$$I_{der} = \frac{I_D}{I_{D(25°C)}} \times 100\,\%$$



T_{sp} = 25 °C; I_{DM} is single pulse

Fig. 2. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

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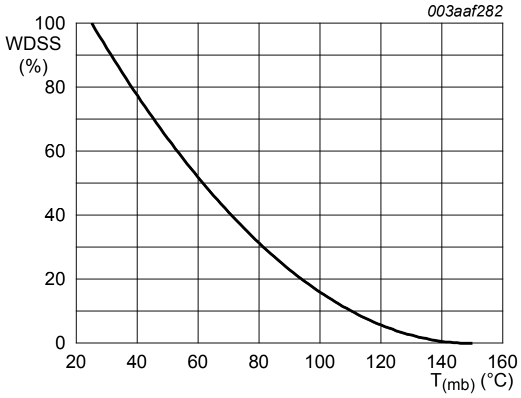

I_D = 2.5 A

Fig. 3. Normalised drain-source non-repetitive avalanche energy as a function of mounting-base temperature

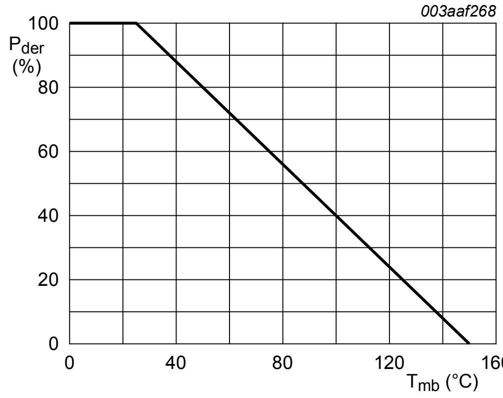

Fig. 4. Normalized total power dissipation as a function of solder point temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25°C)}} \times 100\,\%$$

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point	mounted on any printed-circuit board		-	12	15	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	Mounted on FR4 PCB, mounting pad for drain 6.5 cm^2		-	120	-	K/W

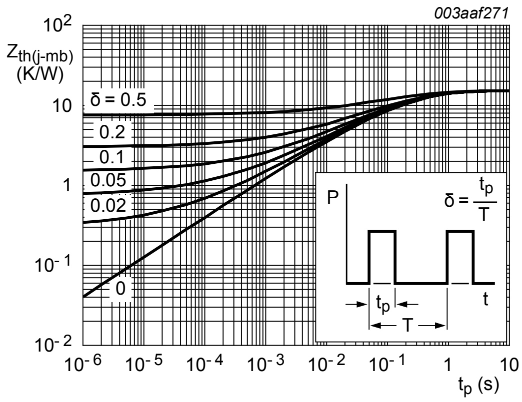

Fig. 5. Transient thermal impedance from junction to solder point as a function of pulse duration

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10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = 0.25 mA; V_{GS} = 0 V; T_j = 25 °C		55	-	-	V
		I_D = 0.25 mA; V_{GS} = 0 V; T_j = -55 °C		50	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	I_D = 1 mA; V_{DS} = V_{GS}; T_j = 150 °C		1.2	-	-	V
		I_D = 1 mA; V_{DS} = V_{GS}; T_j = 25 °C		2	3	4	V
		I_D = 1 mA; V_{DS} = V_{GS}; T_j = -55 °C		-	-	4.4	V
I_{DSS}	drain leakage current	V_{DS} = 55 V; V_{GS} = 0 V; T_j = 25 °C		-	0.05	10	µA
		V_{DS} = 55 V; V_{GS} = 0 V; T_j = 150 °C		-	-	100	µA
I_{GSS}	gate leakage current	V_{GS} = 10 V; V_{DS} = 0 V; T_j = 25 °C		-	0.04	1	µA
		V_{GS} = -10 V; V_{DS} = 0 V; T_j = 25 °C		-	0.04	1	µA
		V_{GS} = 10 V; V_{DS} = 0 V; T_j = 150 °C		-	-	10	µA
		V_{GS} = -10 V; V_{DS} = 0 V; T_j = 150 °C		-	-	10	µA
R_{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 5 A; T_j = 150 °C		-	-	148	mΩ
		V_{GS} = 10 V; I_D = 5 A; T_j = 25 °C		-	65	80	mΩ
$V_{(BR)GSS}$	gate-source breakdown voltage	V_{DS} = 0 V; T_j = 25 °C; I_G = 1 mA		16	-	-	V
		V_{DS} = 0 V; T_j = 25 °C; I_G = -1 mA		16	-	-	V
Dynamic characteristics							
C_{iss}	input capacitance	V_{GS} = 0 V; V_{DS} = 25 V; f = 1 MHz; T_j = 25 °C		-	365	500	pF
C_{oss}	output capacitance			-	110	135	pF
C_{rss}	reverse transfer capacitance			-	60	85	pF
$t_{d(on)}$	turn-on delay time	V_{DS} = 30 V; R_L = 4.3 Ω; V_{GS} = 10 V; $R_{G(ext)}$ = 10 Ω; T_{mb} = 25 °C; I_D = 7 A		-	9	14	ns
t_r	rise time			-	15	25	ns
$t_{d(off)}$	turn-off delay time			-	18	27	ns
t_f	fall time			-	12	18	ns
g_{fs}	transfer conductance	V_{DS} = 25 V; I_D = 5 A; T_j = 25 °C		1	4	-	S
Source-drain diode							
V_{SD}	source-drain voltage	I_S = 5 A; V_{GS} = 0 V; T_j ≥ -55 °C; T_j ≤ 175 °C		-	0.85	1.1	V
t_{rr}	reverse recovery time	I_S = 5 A; dI_S/dt = -100 A/µs; V_{GS} = -10 V; V_{DS} = 30 V; T_j ≥ -55 °C; T_j ≤ 175 °C		-	38	-	ns
Q_r	recovered charge			-	0.2	-	µC

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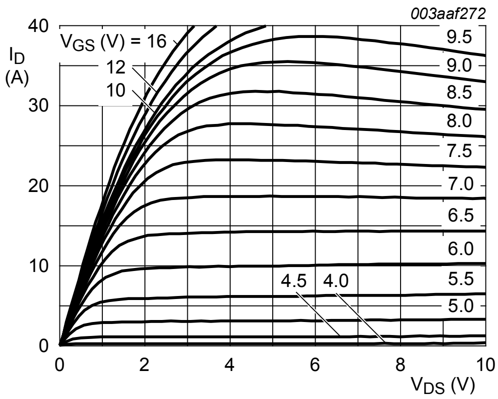
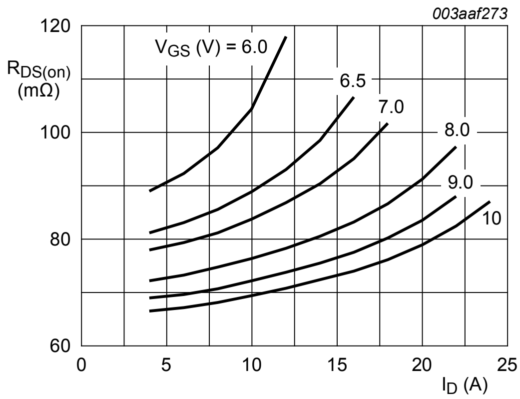


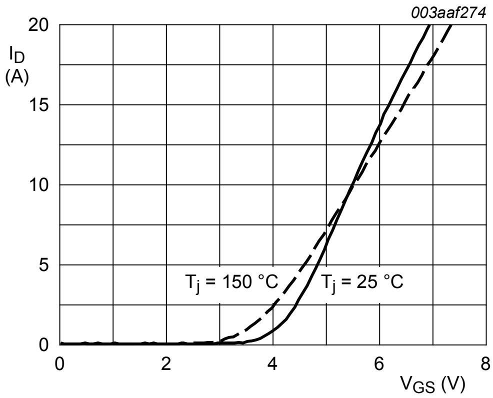
T_j = 25 °C

Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values



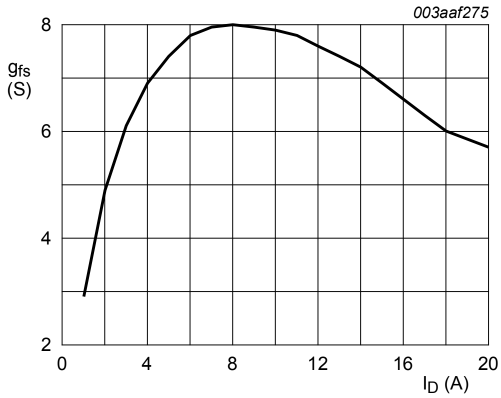
T_j = 25 °C

Fig. 7. Drain-source on-state resistance as a function of drain current; typical values



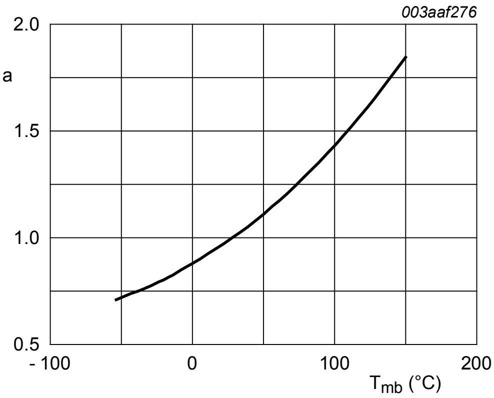
$V_{DS} > I_D \times R_{DSon}$

Fig. 8. Transfer characteristics: drain current as a function of gate-source voltage; typical values



$V_{DS} > I_D \times R_{DSon}$

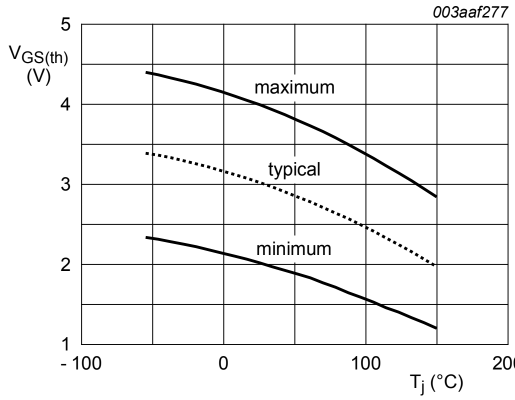
Fig. 9. Forward transconductance as a function of drain current; typical values



I_D = 5 A; V_{GS} = 10 V

Fig. 10. Normalized drain-source on-state resistance factor as a function of junction temperature

$$a = \frac{R_{DSon}}{R_{DSon(25°C)}}$$



I_D = 1 mA; V_{DS} = V_{GS}

Fig. 11. Gate-source threshold voltage as a function of junction temperature

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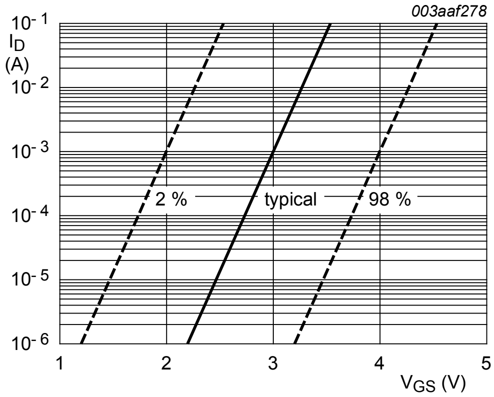
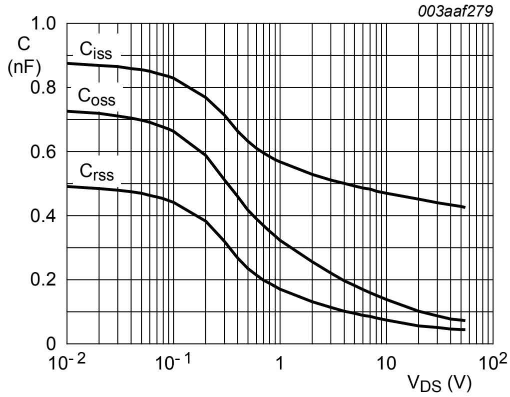


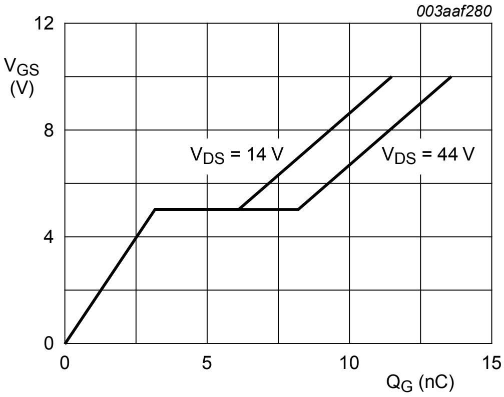
T_j = 25 °C; V_{DS} = V_{GS}

Fig. 12. Sub-threshold drain current as a function of gate-source voltage



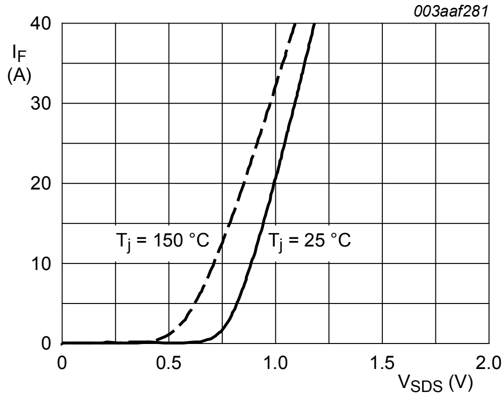
V_{GS} = 0 V; f = 1 MHz

Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



T_j = 25 °C; I_D = 7 A

Fig. 14. Gate-source voltage as a function of gate charge; typical values



V_{GS} = 0 V

Fig. 15. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values

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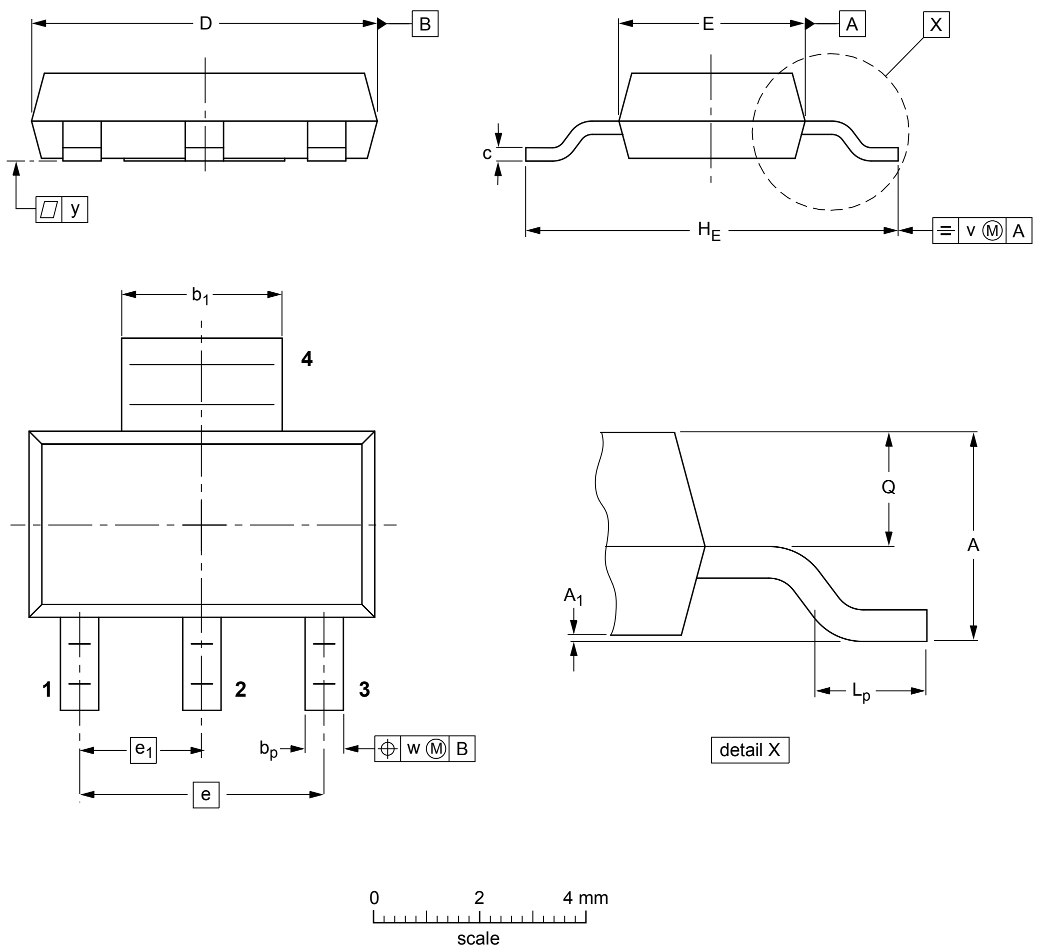
11. Package outline

Plastic surface-mounted package with increased heatsink; 4 leads **SOT223**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b_p	b_1	c	D	E	e	e_1	H_E	L_p	Q	v	w	y
mm	1.8 1.5	0.10 0.01	0.80 0.60	3.1 2.9	0.32 0.22	6.7 6.3	3.7 3.3	4.6	2.3	7.3 6.7	1.1 0.7	0.95 0.85	0.2	0.1	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT223			SC-73			~~04-11-10~~ 06-03-16

Fig. 16. Package outline SC-73 (SOT223)

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".
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13. Contents

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